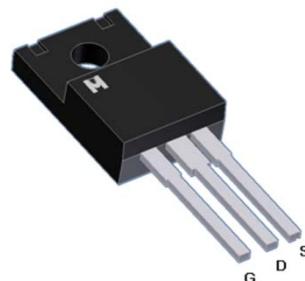
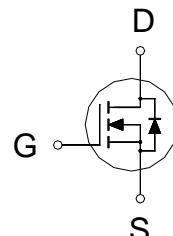


N-Channel Logic Level Enhancement Mode Field Effect Transistor

Product Summary:

BV <sub>DSS</sub>	60V
R <sub>DSON</sub> (MAX.)	5mΩ
I <sub>D</sub>	75A



UIS, R<sub>G</sub> 100% Tested

Pb-Free Lead Plating & Halogen Free



**ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C Unless Otherwise Noted)**

PARAMETERS/TEST CONDITIONS		SYMBOL	LIMITS	UNIT
Gate-Source Voltage		V <sub>GS</sub>	±20	V
Continuous Drain Current	T <sub>C</sub> = 25 °C	I <sub>D</sub>	75	A
	T <sub>C</sub> = 100 °C		45	
Pulsed Drain Current <sup>1</sup>		I <sub>DM</sub>	160	
Avalanche Current		I <sub>AS</sub>	70	
Avalanche Energy	L = 0.1mH, ID=70A, RG=25Ω	E <sub>AS</sub>	245	mJ
Repetitive Avalanche Energy <sup>2</sup>	L = 0.05mH	E <sub>AR</sub>	122	
Power Dissipation	T <sub>C</sub> = 25 °C	P <sub>D</sub>	50	W
	T <sub>C</sub> = 100 °C		20	
Operating Junction & Storage Temperature Range		T <sub>j</sub> , T <sub>stg</sub>	-55 to 150	°C

100% UIS testing in condition of V<sub>D</sub>=30V, L=0.1mH, V<sub>G</sub>=10V, I<sub>L</sub>=40A, Rated V<sub>DS</sub>=60V N-CH

**THERMAL RESISTANCE RATINGS**

THERMAL RESISTANCE	SYMBOL	TYPICAL	MAXIMUM	UNIT
Junction-to-Case	R <sub>θJC</sub>	2.5	2.5	°C / W
Junction-to-Ambient	R <sub>θJA</sub>		65	

<sup>1</sup>Pulse width limited by maximum junction temperature.

<sup>2</sup>Duty cycle ≤ 1%

ELECTRICAL CHARACTERISTICS ( $T_J = 25^\circ\text{C}$ , Unless Otherwise Noted)

PARAMETER	SYMBOL	TEST CONDITIONS	LIMITS			UNIT
			MIN	TYP	MAX	
STATIC						
Drain-Source Breakdown Voltage	$V_{(\text{BR})\text{DSS}}$	$V_{GS} = 0V, I_D = 250\mu\text{A}$	60			V
Gate Threshold Voltage	$V_{GS(\text{th})}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	2.0	3.0	4.0	
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0V, V_{GS} = \pm 20V$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 48V, V_{GS} = 0V$			1	$\mu\text{A}$
		$V_{DS} = 40V, V_{GS} = 0V, T_J = 125^\circ\text{C}$			25	
On-State Drain Current <sup>1</sup>	$I_{D(\text{ON})}$	$V_{DS} = 5V, V_{GS} = 10V$	75			A
Drain-Source On-State Resistance <sup>1</sup>	$R_{DS(\text{ON})}$	$V_{GS} = 10V, I_D = 20A$		4.6	5.0	$\text{m}\Omega$
Forward Transconductance <sup>1</sup>	$g_f$	$V_{DS} = 5V, I_D = 20A$		55		S
DYNAMIC						
Input Capacitance	$C_{iss}$	$V_{GS} = 0V, V_{DS} = 25V, f = 1\text{MHz}$		5085		pF
Output Capacitance	$C_{oss}$			573		
Reverse Transfer Capacitance	$C_{rss}$			190		
Gate Resistance	$R_g$	$V_{GS} = 15\text{mV}, V_{DS} = 0V, f = 1\text{MHz}$		1.5		$\Omega$
Total Gate Charge <sup>1,2</sup>	$Q_g$	$V_{DS} = 30V, V_{GS} = 10V, I_D = 20A$		59		nC
Gate-Source Charge <sup>1,2</sup>	$Q_{gs}$			20		
Gate-Drain Charge <sup>1,2</sup>	$Q_{gd}$			19		
Turn-On Delay Time <sup>1,2</sup>	$t_{d(\text{on})}$	$V_{DS} = 30V, I_D = 1A, V_{GS} = 10V, R_{GS} = 6\Omega$		55		nS
Rise Time <sup>1,2</sup>	$t_r$			150		
Turn-Off Delay Time <sup>1,2</sup>	$t_{d(\text{off})}$			90		
Fall Time <sup>1,2</sup>	$t_f$			160		
SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS ( $T_c = 25^\circ\text{C}$ )						
Continuous Current	$I_s$				75	A
Pulsed Current <sup>3</sup>	$I_{SM}$				160	
Forward Voltage <sup>1</sup>	$V_{SD}$	$I_F = 20A, V_{GS} = 0V$			1.3	V
Reverse Recovery Time	$t_{rr}$	$I_F = 25A, dI_F/dt = 100A/\mu\text{s}$		35		nS
Reverse Recovery Charge	$Q_{rr}$			220		nC

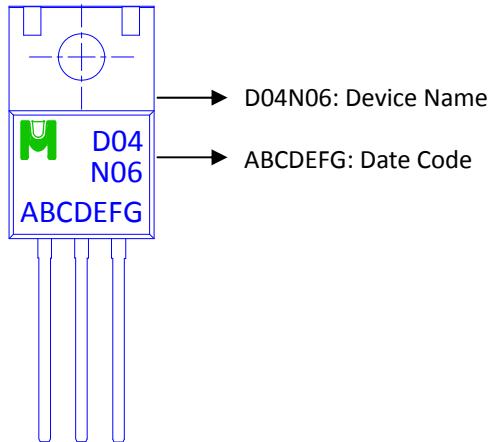
<sup>1</sup>Pulse test : Pulse Width  $\leq 300 \mu\text{sec}$ , Duty Cycle  $\leq 2\%$ .

<sup>2</sup>Independent of operating temperature.

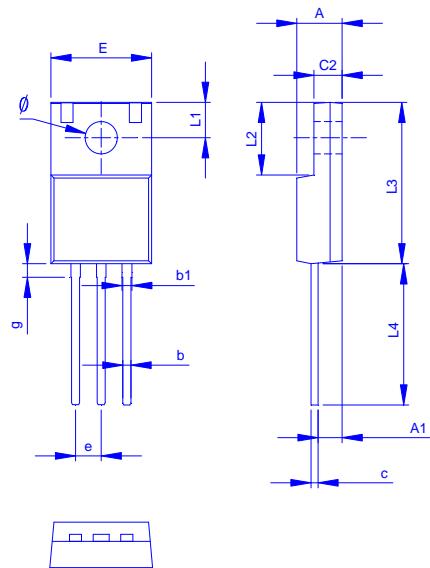
<sup>3</sup>Pulse width limited by maximum junction temperature.

Ordering & Marking Information:

Device Name: EMD04N06FN for TO-220F



Outline Drawing



Dimension in mm

Dimension	A	A1	b	b1	c	c2	E	L1	L2	L3	L4	φ	e	g
Min.	4.30	2.50	0.60	0.60	0.45	2.50	9.70	2.90	6.30	14.70	13.40	3.00	2.35	1.00
Max.	4.70	2.70	0.80	0.90	0.60	2.90	10.30	3.10	6.70	15.30	13.80	3.40	2.75	1.20

TYPICAL CHARACTERISTICS

